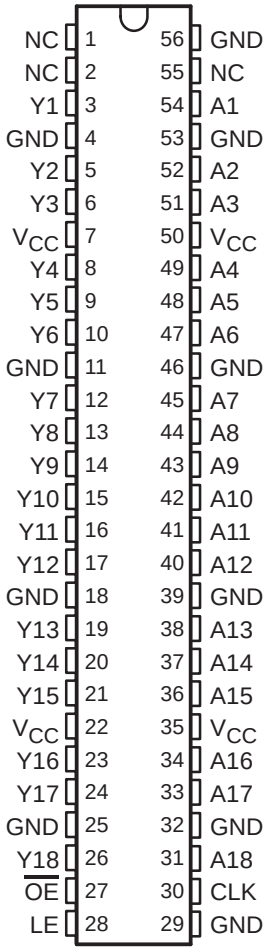
- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation**
- **Member of the Texas Instruments *Widebus*™ Family**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Supports Live Insertion**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages Using 25-mil Center-to-Center Spacings**

DGG OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

description

The SN74LVT16835 is an 18-bit universal bus driver designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

Data flow from A to Y is controlled by the output-enable ($\overline{OE}$) input. This device operates in the transparent mode when the latch-enable (LE) input is high. The A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of the clock. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16835 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the input/output (I/O) pins and functionality of standard small-outline packages in the same printed circuit board area.

The SN74LVT16835 is characterized for operation from –40°C to 85°C.

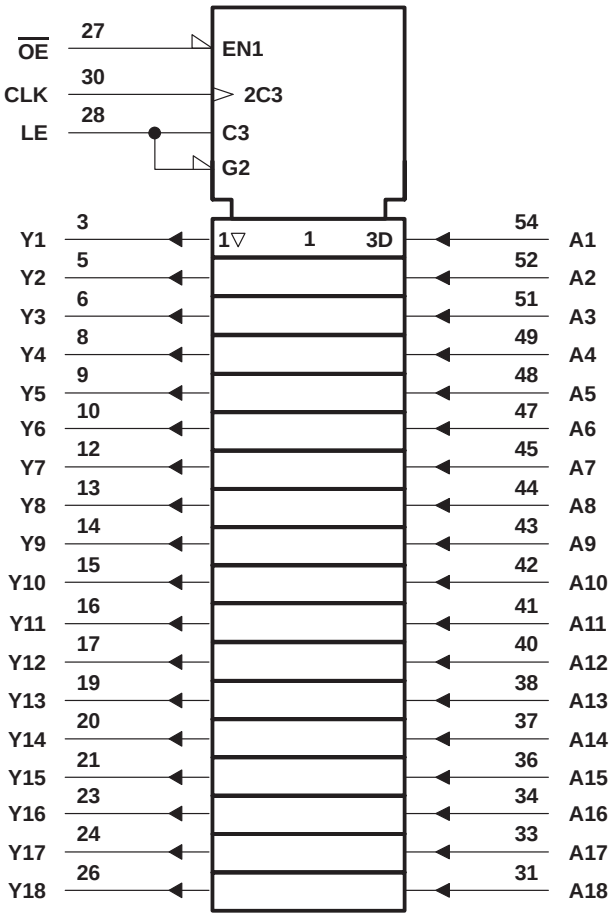
FUNCTION TABLE

INPUTS				OUTPUT
$\overline{OE}$	LE	CLK	A	Y
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	H	X	Y_0†
L	L	L	X	Y_0‡

† Output level before the indicated steady-state input conditions were established, provided that CLK was high before LE went low

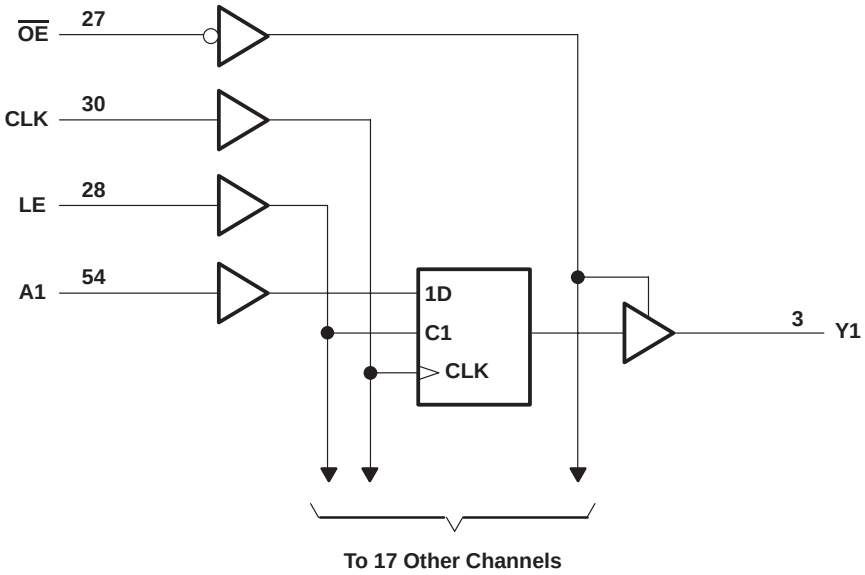
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) . . . . –0.5 V to 7 V
Current into any output in the low state, I_O . . . . . 128 mA
Current into any output in the high state, I_O (see Note 2) . . . . . 64 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 3): DGG package . . . . . 1 W
DL package . . . . . 1.4 W
Operating free-air temperature range, T_A . . . . . –40°C to 85°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage			5.5	V
I_{OH}	High-level output current			–32	mA
I_{OL}	Low-level output current			64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 2.7 V,	I_I = –18 mA				–1.2	V
V_{OH}		V_{CC} = 2.7 V to 3.6 V,	I_{OH} = –100 µA		V_{CC}–0.2			V
		V_{CC} = 2.7 V,	I_{OH} = –8 mA		2.4			
		V_{CC} = 3 V	I_{OH} = –32 mA		2			
V_{OL}		V_{CC} = 2.7 V	I_{OL} = 100 µA				0.2	V
			I_{OL} = 24 mA				0.5	
		V_{CC} = 3 V	I_{OL} = 16 mA				0.4	
			I_{OL} = 32 mA				0.5	
			I_{OL} = 64 mA				0.55	
I_I		V_{CC} = 0 or 3.6 V,	V_I = 5.5 V				10	µA
	Control inputs	V_{CC} = 3.6 V,	V_I = V_{CC} or GND				±1	
	A inputs	V_{CC} = 3.6 V	V_I = V_{CC}				1	
			V_I = 5.5 V				20	
			V_I = 0				–5	
I_{off}		V_{CC} = 0,	V_I or V_O = 0 to 4.5 V				±100	µA
$I_{I(hold)}$	A inputs	V_{CC} = 3 V	V_I = 0.8 V		75			µA
			V_I = 2 V		–75			
I_{OZH}		V_{CC} = 3.6 V,	V_O = 3 V				1	µA
I_{OZL}		V_{CC} = 3.6 V,	V_O = 0.5 V				–1	µA
I_{CC}		V_{CC} = 3.6 V, V_I = V_{CC} or GND	I_O = 0,	Outputs high			0.12	mA
				Outputs low			5	
				Outputs disabled			0.12	
ΔI_{CC}‡		V_{CC} = 3 V to 3.6 V, Other inputs at V_{CC} or GND	One input at V_{CC} – 0.6 V,				0.2	mA
C_i	Control inputs	V_I = 3 V or 0				3.5		pF
	Data pins					4.5		
C_o		V_O = 3 V or 0				11		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

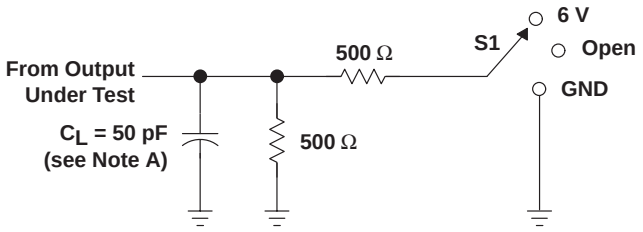
			V_{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	125	MHz
t_w	Pulse duration	LE high	3.3		3.3		ns
		CLK high or low	3.3		3.3		
t_{su}	Setup time	Data before CLK↑	1.6		2.1		ns
		Data before LE↓, CLK high	2.6		1.9		
		Data before LE↓, CLK low	2		1.3		
t_h	Hold time	Data after CLK↑	2		2.1		ns
		Data after LE↓	0.9		1.2		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.3 V			V_{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
f_{max}			150			150		MHz
t_{PLH}	A	Y	1.7	3	5.4		6.8	ns
t_{PHL}			1.6	3.2	5.9		7.7	
t_{PLH}	LE	Y	2.3	4	7		8.5	ns
t_{PHL}			2.7	4.3	7.9		9.7	
t_{PLH}	CLK	Y	2.5	4.1	7.9		9.2	ns
t_{PHL}			3.5	5.4	8.9		10.4	
t_{PZH}	$\overline{OE}$	Y	1.2	3	5		5.9	ns
t_{PZL}			1.5	3	5.8		6.9	
t_{PHZ}	$\overline{OE}$	Y	2.7	4.6	7.4		8.3	ns
t_{PLZ}			2.8	4.7	6.7		7.2	

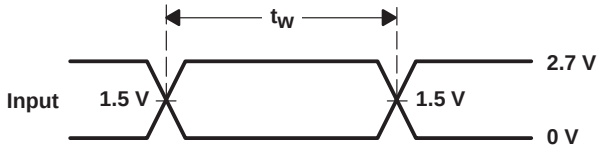
† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

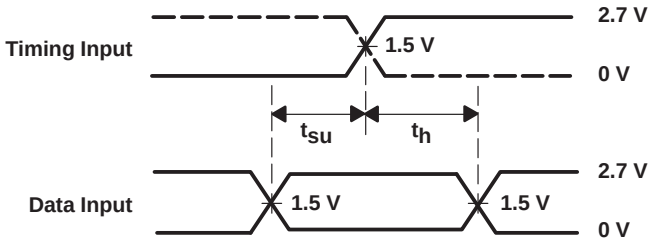


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

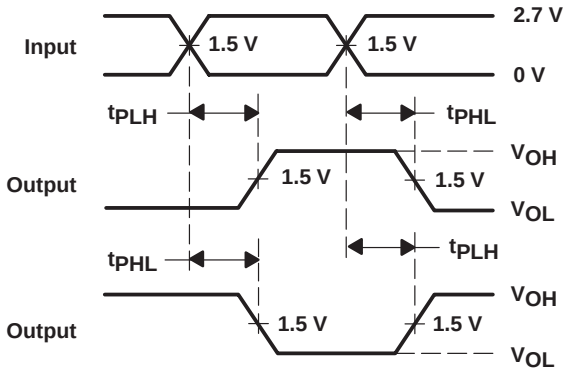
LOAD CIRCUIT



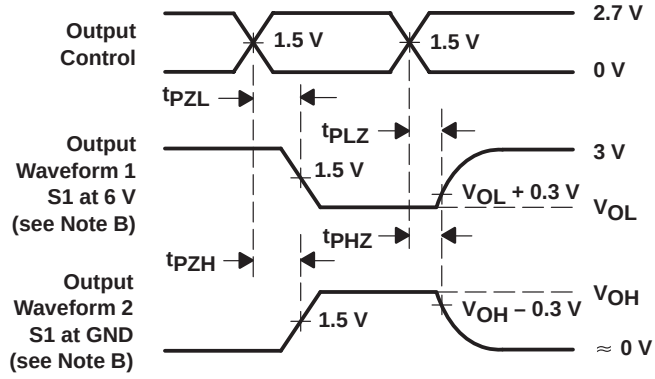
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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